

ABSTRACT

A copper-clad board suitable for making a hole with a carbon dioxide gas laser, which copper-clad board is obtained by disposing a double-side-treated copper foil provided with a metallic-treatment layer having a high absorption rate of a carbon dioxide gas laser energy on at least one surface, at least on an outer layer of a thermosetting resin composition layer such that the metallic-treatment layer is formed on a shiny surface of the copper foil which shiny surface is to be a surface layer, and laminate-forming the double-side-treated copper foil and the thermosetting resin composition layer under heat and pressure, to make an alloy of the metallic-treatment layer and the copper by the above heating, a method of making hole in the above copper-clad board and a printed wiring board comprising the above copper-clad board.